

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chun-Lin LU</td> <td>06/25/2013</td> </tr> <tr> <td>Kai-Chiang WU</td> <td>06/25/2013</td> </tr> <tr> <td>Ming-Kai LIU</td> <td>06/25/2013</td> </tr> <tr> <td>Yen-Ping WANG</td> <td>06/25/2013</td> </tr> <tr> <td>Shih-Wei LIANG</td> <td>06/25/2013</td> </tr> <tr> <td>Ching-Feng YANG</td> <td>06/25/2013</td> </tr> <tr> <td>Chia-Chun MIAO</td> <td>06/25/2013</td> </tr> <tr> <td>Hung-Jen LIN</td> <td>06/25/2013</td> </tr> </tbody> </table>		Name	Execution Date	Chun-Lin LU	06/25/2013	Kai-Chiang WU	06/25/2013	Ming-Kai LIU	06/25/2013	Yen-Ping WANG	06/25/2013	Shih-Wei LIANG	06/25/2013	Ching-Feng YANG	06/25/2013	Chia-Chun MIAO	06/25/2013	Hung-Jen LIN	06/25/2013
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RECEIVING PARTY DATA																			
<table border="1"> <tr> <td>Name:</td> <td>Taiwan Semiconductor Manufacturing Co., Ltd</td> </tr> <tr> <td>Street Address:</td> <td>No. 8, Li-Hsin Road. 6</td> </tr> <tr> <td>Internal Address:</td> <td>Science-Based Industrial Park</td> </tr> <tr> <td>City:</td> <td>Hsin-Chu</td> </tr> <tr> <td>State/Country:</td> <td>TAIWAN</td> </tr> <tr> <td>Postal Code:</td> <td>300-77</td> </tr> </table>		Name:	Taiwan Semiconductor Manufacturing Co., Ltd	Street Address:	No. 8, Li-Hsin Road. 6	Internal Address:	Science-Based Industrial Park	City:	Hsin-Chu	State/Country:	TAIWAN	Postal Code:	300-77						
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CORRESPONDENCE DATA																			
Fax Number:	7032058050																		
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>																			
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OP \$40.00 13927972

ATTORNEY DOCKET NUMBER:	0941-2781PUS1
NAME OF SUBMITTER:	Mussie B. Beyene
Signature:	/Mussie B. Beyene/
Date:	07/03/2013
Total Attachments: 2 source=2013-07-03 - Assignment - 0941-2781PUS1#page1.tif source=2013-07-03 - Assignment - 0941-2781PUS1#page2.tif	

ASSIGNMENT

WHEREAS, Chun-Lin LU, Kai-Chiang WU, Ming-Kai LIU, Yen-Ping WANG, Shih-Wei LIANG, Ching-Feng YANG, Chia-Chun MIAO, and Hung-Jen LIN

hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **MECHANISMS FOR FORMING HYBRID BONDING STRUCTURES WITH ELONGATED BUMPS**

Filed: June 26, 2013 Serial No. 13/927,972
 Executed on: June 25, 2013

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd. of No.8, Li-Hsin Road. 6: Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. hereinafter referred to as ASSIGNEES, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

ASSIGNMENT

2013.6.25 Chun-Lin Lu
 Date Name: Chun-Lin LU (Last name: LU)

2013.6.25 Kai-Chiang Wu
 Date Name: Kai-Chiang WU (Last name: WU)

2013.6.25 Ming-Kai Liu
 Date Name: Ming-Kai LIU (Last name: LIU)

2013.6.25 Yen-Ping Wang
 Date Name: Yen-Ping WANG (Last name: WANG)

2013.6.25 Shih-Wei Liang
 Date Name: Shih-Wei LIANG (Last name: LIANG)

2013.6.25 Ching-feng Yang
 Date Name: Ching-Feng YANG (Last name: YANG)

2013.6.25 Chia-Chun Miao
 Date Name: Chia-Chun MIAO (Last name: MIAO)

2013.6.25 Hung-Jen Lin
 Date Name: Hung-Jen LIN (Last name: LIN)